

D3CE60K

Fast Recovery Diodes 600V, 3A

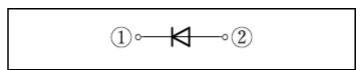
Feature

- Ultra-small SMD
- Ultra-thin PKG=1.0mm
- High Voltage
- · Based on AEC-Q101
- · Pb free terminal
- RoHS:Yes

OUTLINE



Equivalent circuit



Absolute Maximum Ratings (unless otherwise specified : Tl=25°C)

Item	Symbol	Conditions	Ratings	Unit
Storage temperrature	Tstg		-55 to 150	°C
Junction temperature	Tj		-55 to 150	°C
Repetitive peak reverse voltage	V_{RRM}		600	V
Average forward current	I _F (AV)	50Hz sine wave, Resistance load, TI=78°C	3	Α
Average forward current	I _F (AV)	50Hz sine wave, Resistance load, TI=103°C	2.2	Α
Average forward current	I _F (AV)	50Hz sine wave, Resistance load, On glass-epoxy substrate, Ta=25°C *	0.97	Α
Average forward current	I _F (AV)	50Hz sine wave, Resistance load, On glass-epoxy substrate, Ta=25°C *	0.69	Α
Surge forward current	I _{FSM}	50Hz sine wave, Non-repetitive 1 cycle, Peak value, Tj=25°C	50	Α
Surge forward current	I _{FSM1}	tp=1ms, Sine wave, Non-repetitive, Peak value, Tj=25°C	95	Α

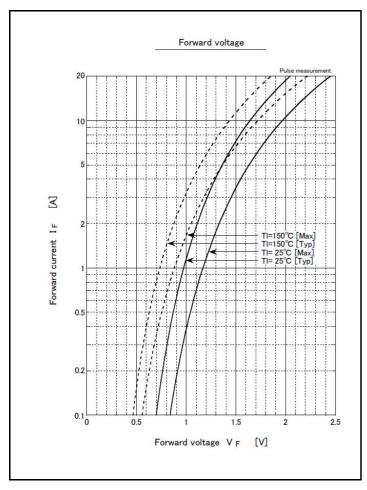
^{* :} See the original Specifications

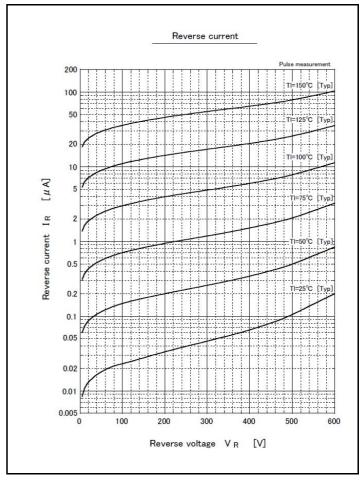
Electrical Characteristics (unless otherwise specified : TI=25°C)

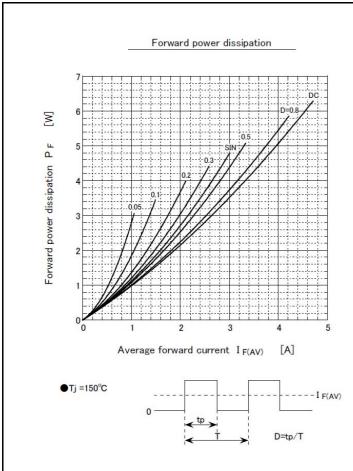
Item	Symbol	Conditions	Ratings			Unit
			MIN	TYP	MAX	Offic
Forward voltage	V _F	IF=3A, Pulse measurement			1.45	V
Reverse current	I _R	VR=600V, Pulse measurement			10	μΑ
Reverse recovery time	trr	IF=0.5A, IR=1.0A, 0.25IR			80	ns
Reverse recovery time	trr	IF=1.0A, VR=30V, di/dt=-50A/µs, 0.25IR			64	ns
Reverse recovery time	trr	IF=1.0A, VR=420V, di/dt=-50A/μs, 0.25IR			76	ns
Total capacitance	Ct	f=1MHz, VR=10V		18		pF
Thermal resistance	Rth(j-l)	Junction to lead			15	°C/W
Thermal resistance	Rth(j-a)	Junction to ambient, On glass-epoxy substrate *			115	°C/W
Thermal resistance	Rth(j-a)	Junction to ambient, On glass-epoxy substrate *			172	°C/W

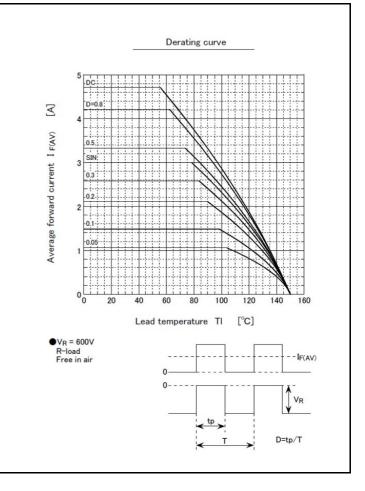
^{*} :See the original Specifications

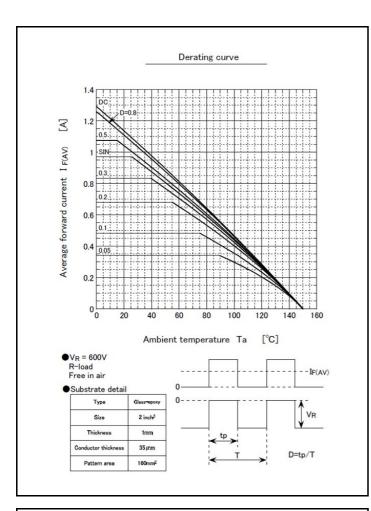
CHARACTERISTIC DIAGRAMS

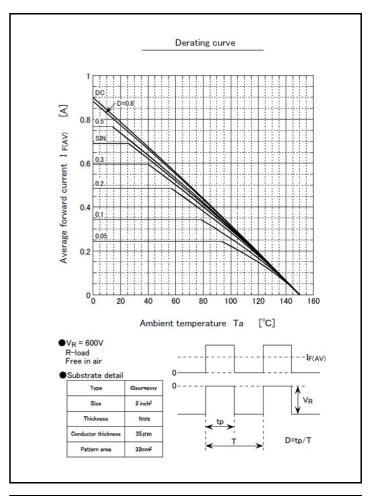


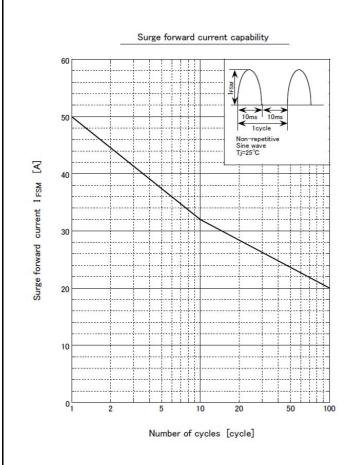


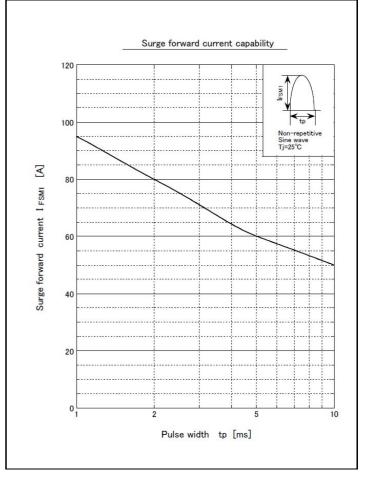


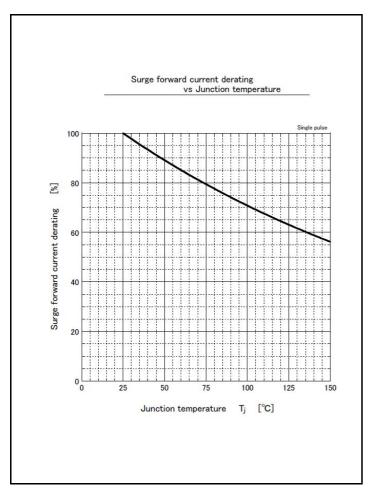


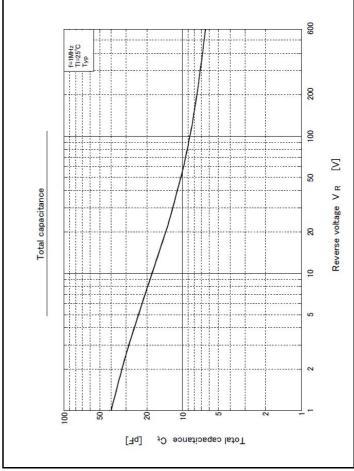


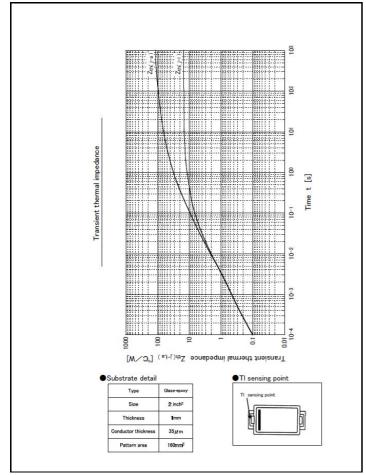


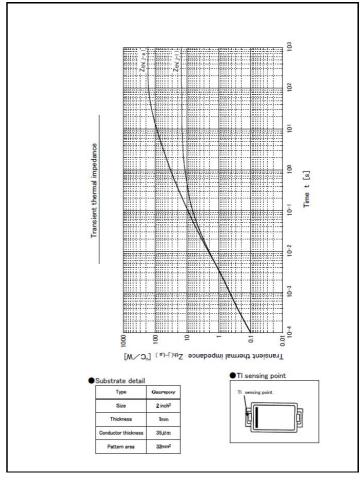








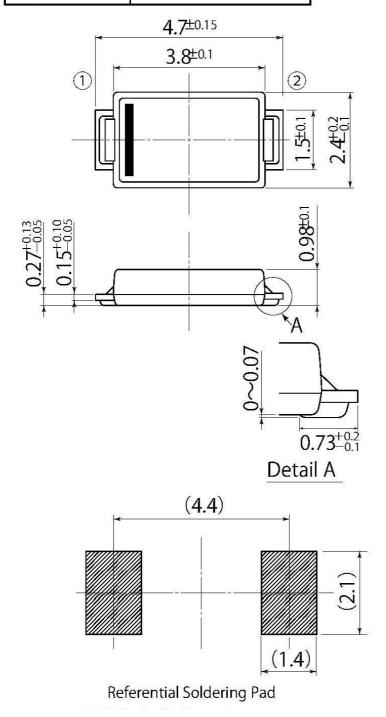


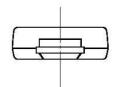


scale: 10/1

B5

JEDEC Code	_
JEITA Code	SC-110B
House Name	CE





[•] Optimize soldering pad to the board design and soldering condition.

Notes

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[Special applications]

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